

04R-00432-2.0

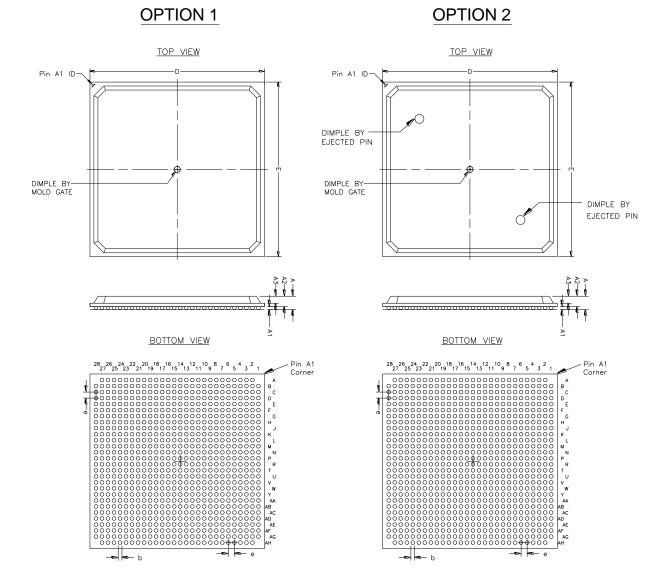
780-Pin FineLine Ball-Grid Array (FBGA) - Wire Bond - A:2.40

- All dimensions and tolerances conform to ASME Y14.5M 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information		
Description	Specification	
Ordering Code Reference	F	
Package Acronym	FBGA	
Substrate Material	BT	
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)	
JEDEC Outline Reference	MS-034 Variation: AAM-1	
Lead Coplanarity	0.008 inch (0.20 mm)	
Weight	3.0 g (Тур.)	
Moisture Sensitivity Level	Printed on moisture barrier bag	

Package Outline Di	Package Outline Dimension Table				
	Millimeters				
Symbol	Min.	Nom.	Max.		
А	2.10	2.25	2.40		
A1	0.40	0.50	0.60		
A2	1.50	1.75	2.00		
A3	1.12	1.17	1.22		
D	29.00 BSC				
E	29.00 BSC				
b	0.50	0.60	0.70		
e	1.00 BSC				

Package Outline



Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
September 2011	1.0	Initial release
December 2012	2.0	Add option 2 package outline in page.2.



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